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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 35010.4-2018

**Semiconductor die products -- Part 4: Requirements for die
users and suppliers**

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Foreword

GB/T 35010 "Semiconductor chip products" is divided into the following parts.

- Part 1. Procurement and use requirements;
- Part 2. Data exchange format;
- Part 3. Guidelines for handling, packaging and storage;
- Part 4. Chip user and supplier requirements;
- Part 5. Electrical Simulation Requirements;
- Part 6. Thermal Simulation Requirements;
- Part 7. XML format for data exchange;
- Part 8. EXPRESS format for data exchange.

This part is part 4 of GB/T 35010.

This section uses the translation method identical to the use of IEC /T R62258-4.2012 "Semiconductor chip products Part 4. Chip users and

Supplier Information Form.

The Chinese documents that have a consistent correspondence with the normatively quoted international documents in this section are as follows.

- GB/T 2900 (all parts) Electrical terminology [IEC 60050 (all parts)].

This section made the following editorial changes.

- Consider adapting to our country's standard system, change the name to "Semiconductor chip product Part 4. Chip users and suppliers Claim".

1 Scope

This part of GB/T 35010 is used to guide the production, supply and use of semiconductor chip products. Semiconductor chip products include.

- * Wafers;
- * Single bare chip;
- * Chips and wafers with interconnect structures;

Small-sized or partially packaged chips and wafers.

This section contains the information sheet for the other parts of GB/T 35010. This section applies to suppliers and users of chip products.

Consultation and signing. The purpose is to help manufacturers of all chip product supply chains refer to GB/T 35010.1-2018 and

The relevant requirements of the GB/T 35010.2-2018 standard are implemented.

It should be noted that the tables in this section constitute a list of information that may be provided on the actual product and all areas involved.

The information is lacking. Here, this information may need to be included for different markets.

2 Normative references

The following documents are indispensable for the application of this document. For dated references, only dated versions apply to this article

Pieces. For undated references, the latest version (including all amendments) applies to this document.

GB/T 35010.1-2018 semiconductor chip products - Part 1. Procurement and use requirements (IEC 62258-1.2009, IDT)

GB/T 35010.2-2018 Semiconductor chip products Part 2. Data exchange format (IEC 62258-2.2011, IDT)

IEC 60050 (all parts) International Electrotechnical Vocabulary

3 Terms and definitions

The terms and definitions defined in IEC 60050 (all parts) and GB/T 35010.2-2018 apply to this document.

4 General

In order to be consistent with GB/T 35010.1-2018, it is necessary for chip device suppliers to provide products for device users to design and adopt.

Necessary and sufficient information for the entire process of purchasing, manufacturing, and testing. The information sheet in Appendix A provides the basic content and format of information exchange.

To meet the standards.

The reference terms cited in this section are in the standards GB/T 35010.1-2018 and GB/T 35010.2-2018, which apply only to this

Version standards. Appendix A contains the required information that is not covered by the above standards but will be included in subsequent editions. And, some terms may

Does not fully comply with other parts of GB/T 35010. For example, the term "pad" (or "bonding zone") is replaced in this section by "Export"

end".

At the same time, most of the information provided should meet the relevant standards and be disclosed in the public domain, and the information source can be in the form of manufacturer data tables.

The traceability of the form does not require the manufacturer to assume the obligation of information disclosure. Any information involving patent or business sensitive information, manufacturers can adopt

Take a non-disclosed form for protection.